AEC/APC Symposium Asia 2025 SPONSORSHIP and Exhibition

November 25-26, 2025, Fukuoka, Japan

Hidetaka Nishimura
Chairman, AEC/APC Symposium Asia 2025 Executive Committee
Renesas Electronics Corporation

Shunichi Shibuki
Chairman, AEC/APC Symposium Asia 2025 Program Committee
Sony Semiconductor Manufacturing Corporation

It is our great pleasure to announce that the 10th annual AEC/APC Symposium Asia 2025 will be held on November 25-26, 2025, at Fukuoka International Congress Center, FUKUOKA CONVENTION CENTER, Fukuoka, Japan which is sponsored by ISSM (International Symposium on Semiconductor Manufacturing). The program consists of keynote speeches, tutorial speeches, oral speeches, poster presentations and supplier exhibition. This year, the symposium puts the subtitle” Evolution of AECAPC through Fusion of Domain Knowledge and AI/ML”.

AEC/APC Symposium Asia continues to contribute to the growth of the semiconductor industry through its infrastructure for networking, discussion, and information sharing among the world's professionals. We would like you to cooperate with us by supporting the 10th anniversary of AEC/APC Symposium Asia.

Please see the benefit of AEC/APC Symposium Asia 2025 sponsorship.

About AEC/APC Symposium

AEC/APC symposium calls its annual conference in North America, Europe, and Asia. The suppliers of the device, the equipment, the material, the software, the sensor, and the metrology shall meet, and discuss the more intelligent and the higher productive manufacturing system in the conferences. The conference is held in Taiwan and Japan every other year. AEC/APC is called the core of the scientific manufacturing technology. The technology has created the extensive progress of the productivity improvement and the yield improvement in the semiconductor manufacturing area. The technology discussed in the conferences has been applied and used in the process technology of LCD,PV and Battery.

In Japan, the 10th conference is called in this year. Since 2007, the conference has discussed the scientific manufacturing technology using the data which can monitor the manufacturing equipment and the process conditions.

The symposium probide an excellent opportunity among the technical authorities from Japan and from out of Japan to share their knowledge and technologies in AEC/APC area. The symposium can also be a very good chance for the professionals of the process control industry such as semiconductor to meet and discuss.

Today, this area already forms the core part of the manufacturing engineering technology.

The role of this symposium is very important, since people can share the information and the directions of the process control improvement, the equipment productivity improvement, and the material source reduction for the future.

*AEC: Advanced Equipment Control, APC: Advanced Process Control

Conference Overview

1. Date: November 25-26, 2025

2. Location: Fukuoka International Congress Center, FUKUOKA CONVENTION CENTER
2-1 Sekijo-machi, Hakata-ku, Fukuoka City 812-0032
TEL: 092-262-4111 FAX: 092-262-4701

3. Sponsored by
International Symposium on Semiconductor Manufacturing (ISSM)
AEC/APC Symposium Asia Committee

4. Supported by
Semiconductor Equipment Association of Japan (SEAJ)
Semiconductor Equipment and Materials International (SEMI)

5. Endorsement by
The Japan Institute of Electronics Packaging

6. Partner Conference
Dry Process Symposium (DPS)
SWTest Asia 2025

7. AEC/APC Symposium Asia 2025 – Registration Fee

Category		JP Yen (Tax included)
Regular	Early bird (October 24, 2025 due)	¥33,000
	Regular (On and after October 25, 2025)	¥39,600
Student	The registration fee for student speakers is waived. Please contact to the secretariat	¥5,500
Bulk	(Group 5)	¥145,200(¥29,040 per person)
	(Group 10)	¥264,000(¥26,400 per person)
Sponsors (Complimentary tickets)	The registration information for the complimentary ticket(s) will be provided separately.	

The above registration fee includes 2-day lecture sessions, networking reception on November 25, lunch on November 26, and online proceedings.

AEC/APC Symposium Asia 2025 Sponsorship Fee

	Platinum	Gold	Silver	Bronze
Sponsorship Fee (Non-taxation)	¥800,000	¥500,000	¥300,000	¥100,000
AEC/APC Symposium Asia Complimentary Ticket(s) (Free)				
Free ticket(s) for AEC/APC Symposium Asia (Tutorial session excluded)	12	7	4	1
AEC/APC Symposium Asia Website				
Company logo placed on website	Upper	Middle	Lower	Lower
Link to company website	Yes	Yes	Yes	Yes
AEC/APC Symposium Asia Proceedings (Download) & Brochure				
Recognition of sponsorship in meeting materials along with company logo and link to corporate website (User would need to have Internet access when viewing the proceedings)	Upper	Middle	Lower	Lower
Company logo printed in color on the brochure on site	Upper	Middle	Lower	Lower
AEC/APC Symposium Asia Screen at site				
Company logo on the screen of interval	Upper	Middle	Lower	Lower
Company logo poster at the Symposium Room	Upper	Middle	Lower	Lower
List				
Registrant List (Name, Affiliation, email. Only who accepted to provide to the sponsors.)	○	○	×	×

★AEC/APC Symposium Asia 2025 Exhibit Fee

Exhibit fee (1 booth) applied with any of above sponsorship (10% tax to be added)	¥120,000
Exhibit only fee (10% tax to be added)	¥150,000

AEC/APC Symposium Asia Organization

Japan Executive Committee

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Japan Program Committee

Chair	Shunichi Shibuki	Sony Semiconductor Manufacturing Corporation
Vice-Chair	Sumika Arima	University of Tsukuba
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	Tomoya Tanaka	Tower Partners Semiconductor Co., Ltd.
	Takayuki Matsumoto	United Semiconductor Japan Co., Ltd.

AEC/APC Symposium Asia Advisor

Advisor	Koji Maekawa	Addison Clear Wave Coatings Inc.

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